1-178313-2 - ACTIVE

Dynamic Series | Dynamic 3000 Series

TE Internal #: 1-178313-2 PCB Mount Header, Vertical, Wire-to-Board, 3 Position, .15 in [3.81 mm] Centerline, Fully Shrouded, Gold, Through Hole - Solder, Dynamic 3000 Series

View on TE.com >

Connectors > PCB Connectors > PCB Headers & Receptacles > Header Assembly: Wire-to-Board, 15A, gold or tin plated



Connector System: Wire-to-Board Number of Positions: **3**

Number of Rows: 1

Centerline (Pitch): 3.81 mm [.15 in]

PCB Mount Orientation: Vertical

All Header Assembly: Wire-to-Board, 15A, gold or tin plated (120)



Features

Product Type Features

Connector System	Wire-to-Board
Header Type	Fully Shrouded
Sealable	No
Connector & Contact Terminates To	Printed Circuit Board
PCB Connector Assembly Type	PCB Mount Header
Configuration Features	
Number of Positions	3
Number of Rows	1
PCB Mount Orientation	Vertical
Body Features	
Primary Product Color	Black
Contact Features	

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Contact Mating Area Plating Material Thickness	.38 μm[15 μin]
Contact Mating Area Plating Material	Gold
Contact Type	Pin
Contact Current Rating (Max)	12 A
Termination Features	
Termination Method to Printed Circuit Board	Through Hole - Solder
Mechanical Attachment	
Mating Alignment Type	Polarization
Mating Retention	With
PCB Mount Retention Type	Retention Leg
Connector Mounting Type	Board Mount
Mating Alignment	With
PCB Mount Alignment	Without
PCB Mount Retention	With
Housing Features	
Housing Material	Polyester GF
Centerline (Pitch)	3.81 mm[.15 in]

Usage Conditions

Operating Temperature Range	-55 – 105 °C[-67 – 221 °F]
Operation/Application	
Circuit Application	Power & Signal
Industry Standards	
UL Flammability Rating	UL 94V-0
Packaging Features	
Packaging Type	Box, Tube
Product Compliance For compliance documentation, visit the product page on TE.com>	
EU RoHS Directive 2011/65/EU	Compliant
EU ELV Directive 2000/53/EC	Compliant
China RoHS 2 Directive MIIT Order No 32, 2016 EU REACH Regulation (EC) No. 1907/2006	No Restricted Materials Above Threshold

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Current ECHA Candidate List: JAN 2022 (223) Candidate List Declared Against: JAN 2022 (223) Does not contain REACH SVHC

Not Low Halogen - contains Br or Cl > 900 ppm.

Wave solder capable to 265°C

Halogen Content

Solder Process Capability

Product Compliance Disclaimer

This information is provided based on reasonable inquiry of our suppliers and represents our current actual knowledge based on the information they provided. This information is subject to change. The part numbers that TE has identified as EU RoHS compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, mercury, PBB, PBDE, DBP, BBP, DEHP, DIBP, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2011/65/EU (RoHS2). Finished electrical and electronic equipment products will be CE marked as required by Directive 2011/65/EU. Components may not be CE marked. Additionally, the part numbers that TE has identified as EU ELV compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, and mercury, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2000/53/EC (ELV). Regarding the REACH Regulation, the information TE provides on SVHC in articles for this part number is based on the latest European Chemicals Agency (ECHA) 'Guidance on requirements for substances in articles' posted at this URL: https://echa.europa.eu/guidance-documents/guidance-on-reach

Compatible Parts

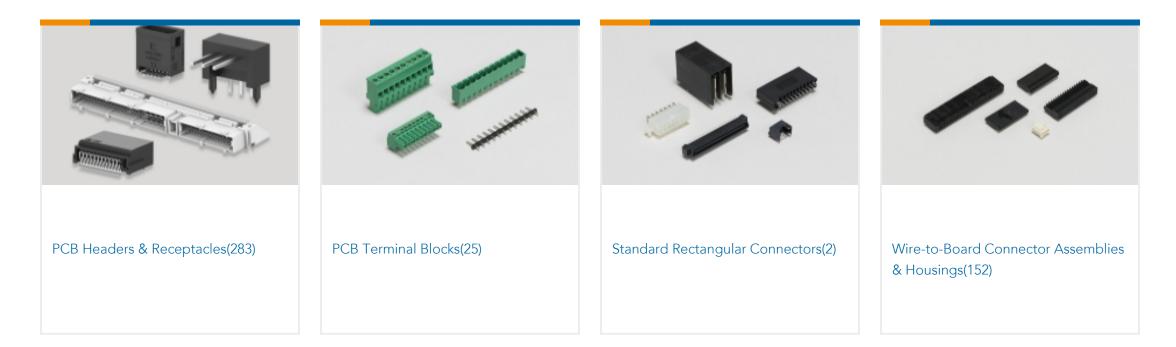


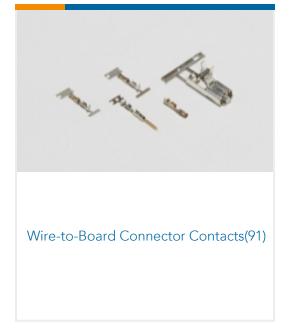
Also in the Series | Dynamic 3000 Series



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Customers Also Bought



DYNAMIC 1100D HDR ASSY V 26P XBLACK GOLD Header Assembly: Wire-to-Board, 15A, gold or tin plated Header Assembly: Wire-to-Board, 15A, gold or tin plated

Documents

Product Drawings DYNAMIC D3100 HDR V 3P ASSY

English

CAD Files

3D PDF

3D

Customer View Model

ENG_CVM_CVM_1-178313-2_J.2d_dxf.zip

English

Customer View Model

ENG_CVM_CVM_1-178313-2_J.3d_igs.zip

English

Customer View Model

ENG_CVM_CVM_1-178313-2_J.3d_stp.zip

English

By downloading the CAD file I accept and agree to the **Terms and Conditions** of use.

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Datasheets & Catalog Pages

1-1773721-5_DYNAMIC_SERIES_QRG

English

1-1773732-4_DYNAMIC_SERIES_CATALOG_ENGLISH

Japanese

1-1773732-4_DYNAMIC_SERIES_CATALOG_ENGLISH

English

Product Specifications

Product Specification

English

Product Environmental Compliance MD_1-178313-2_121120151147_dmtec

English

MD_1-178313-2_121120151147_dmtec

English

Agency Approvals TUV Certificate

English